



MJ P-Channel Enhancement Mode Power MOSFET

Description

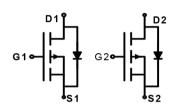
The MJ4953 uses advanced trench technology to provide excellent R_{DS(ON)}, low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a load switch or in PWM applications.

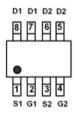
General Features

- ♦ V_{DS} =-30V, I_{D} =-5.1A $R_{DS(ON)}$ <90mΩ @ V_{GS} =-4.5V $R_{DS(ON)}$ <55mΩ @ V_{GS} =-10V
- ◆ High power and current handing capability
- ◆ Lead free product is acquired
- ◆ Surface Mount Package

Application

- ◆ PWM applications
- ◆ Load switch
- ◆ Power management







Schematic diagram

Marking and pin assignment

SOP-8 top view

Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
4953	MJ4953	SOP-8	Ø330mm	12mm	2500 units

Absolute Maximum Ratings (T_A=25℃ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	VDS	-30	V
Gate-Source Voltage	Vgs	±20	V
Drain Current-Continuous	lo	-5.1	А
Drain Current-Pulsed (Note 1)	IDM	-20	А
Maximum Power Dissipation	Po	2.5	W
Operating Junction and Storage Temperature Range	Тл ,Тѕтс	-55 To 150	°C

Thermal Characteristic

Thermal Resistance, Junction-to-Ambient (Note 2)	RθJA	50	°C/W
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Electrical Characteristics (T_A=25℃ unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BVDSS	V _{GS} =0V,I _D =-250µA	-30	-33	-	V
Zero Gate Voltage Drain Current	loss	V _{DS} =-24V,V _{GS} =0V	-	-	-1	μA
Gate-Body Leakage Current	lgss	V _{DS} =±20V,V _{DS} =0V	-	-	±100	nA
On Characteristics (Note 3)	·					
Gate Threshold Voltage	VGS(th)	V _{DS} =V _{GS} ,I _D =-250μA	-1.1	-1.6	-2.1	V
Ducin Course On Otata Parinten	D	V _{GS} =-10V, I _D =-5.1A	-	43	55	mΩ
Drain-Source On-State Resistance	Rds(on)	V _{GS} =-4.5V, I _D =-4.2A	-	62	90	mΩ
Forward Transconductance	grs	V _{DS} =-15V,I _D =-4.5A	4	7	-	S
Dynamic Characteristics (Note 4)				'		'
Input Capacitance	Clss		-	520	-	PF
Output Capacitance	Coss	V _{DS} =-15V,V _{GS} =0V F=1.0MHz	-	130	-	PF
Reverse Transfer Capacitance	Crss		-	70	-	PF
Switching Characteristics (Note 4)						
Turn-on Delay Time	t _{d(on)}		-	7	-	nS
Turn-on Rise Time	tr	V _{DD} =-15V,I _D =-1A	-	13	-	nS
Turn-Off Delay Time	t _{d(off)}	V _{GS} =-10V,R _{GEN} =6Ω	-	14	-	nS
Turn-Off Fall Time	tf		-	9	-	nS
Total Gate Charge	Qg		-	11	-	nC
Gate-Source Charge	Qgs	V _{DS} =-15V,I _D =-5.1A V _{GS} =-10V	-	2.2	-	nC
Gate-Drain Charge	Q _{gd}		-	3	-	nC
Drain-Source Diode Characteristics		I			I	
Diode Forward Voltage (Note 3)	Vsp	V _{GS} =0V,I _S =-5.1A	-	_	-1.2	V

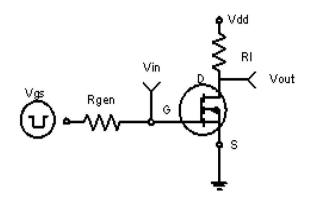
Notes:

- $\textcircled{1} \ \mathsf{Repetitive} \ \mathsf{Rating:} \ \mathsf{Pulse} \ \mathsf{width} \ \mathsf{limited} \ \mathsf{by} \ \mathsf{maximum} \ \mathsf{junction} \ \mathsf{temperature}.$
- ② Surface Mounted on FR4 Board, $t \le 10$ sec.
- ③ Pulse Test: Pulse Width ≤ 300 μ s, Duty Cycle ≤ 2%.
- ④ Guaranteed by design, not subject to production



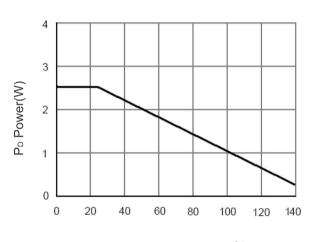


Typical Electrical and Thermal Characteristics



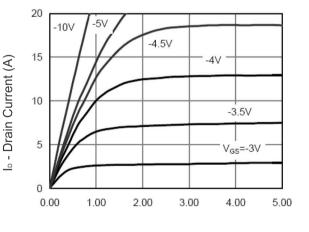
 $\mathbf{t}_{\mathsf{d(on)}}$ t_{d(off)} V_{out} **INVERTED** V_{IN} 50% 50% **PULSE WIDTH**

Figure 1 Switching Test Circuit



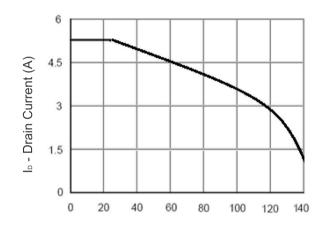
T_J-Junction Temperature(°C)

Figure 3 Power Dissipation



Vds Drain-Source Voltage (V) Figure 5 Output Characteristics

Figure 2 Switching Waveforms



T_J-Junction Temperature(°C) Figure 4 Drain Current

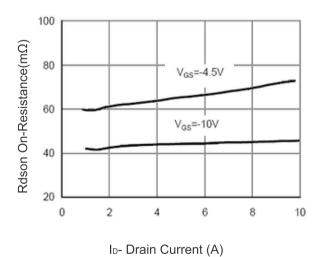
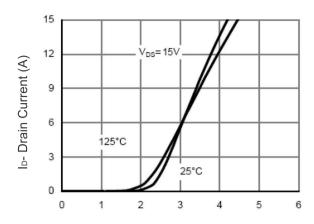


Figure 6 Drain-Source On-Resistance

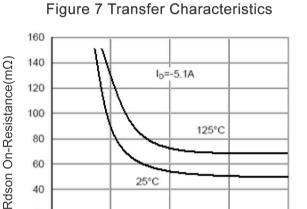


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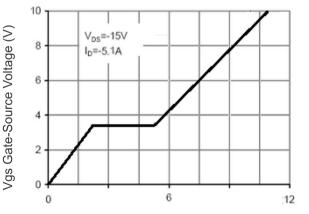


Vgs Gate-Source Voltage (V)

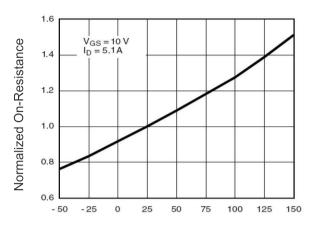


Vgs Gate-Source Voltage (V) Figure 9 Rdson vs Vgs

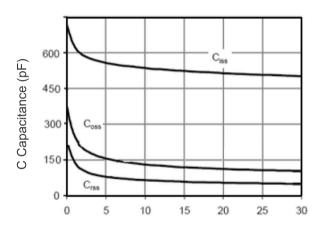
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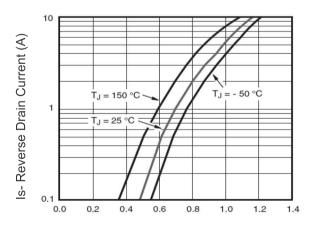
Qg Gate Charge (nC)
Figure 11 Gate Charge



T_J-Junction Temperature(°C)
Figure 8 Drain-Source On-Resistance



Vds Drain-Source Voltage (V)
Figure10 Capacitance vs Vds

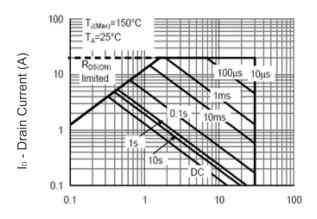


Vsd Source-Drain Voltage (V)
Figure 12 Source- Drain Diode Forward

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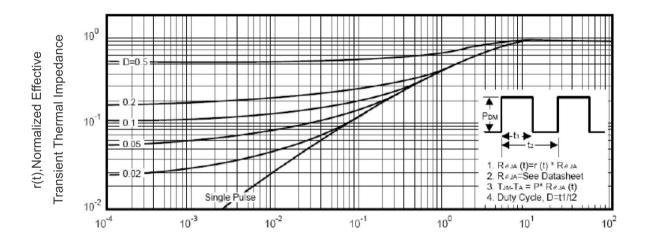






Vds Drain-Source Voltage (V)

Figure 13 Safe Operation Area



Square Wave Pluse Duration(sec)

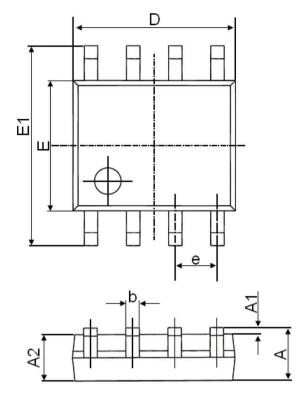
Figure 14 Normalized Maximum Transient Thermal Impedance

θ





SOP-8 Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches		
	Min.	Max.	Min.	Max.	
Α	1.350	1.750	0.053	0.069	
A1	0.100	0.250	0.004	0.010	
A2	1.350	1.550	0.053	0.061	
b	0.330	0.510	0.013	0.020	
С	0.170	0.250	0.006	0.010	
D	4.700	5.100	0.185	0.200	
E	3.800	4.000	0.150	0.157	
E1	5.800	6.200	0.228	0.244	
е	1.270(BSC)		0.050(BSC)		
L	0.400	1.270	0.016	0.050	
θ	0°	8°	0°	8°	





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